



## Material Content Data Sheet



<b>Sales Product Name</b>		SPD04N50C3		<b>Issued</b>		19. July 2018		
<b>MA#</b>		MA001145696						
<b>Package</b>		PG-TO252-3-313		<b>Weight*</b>		318.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.265	1.02	1.02	10240	10240
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		462	
	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	copper	7440-50-8	147.096	46.14	46.20	461320	461921
wire	non noble metal	aluminium	7429-90-5	0.527	0.17	0.17	1654	1654
encapsulation	organic material	carbon black	1333-86-4	1.405	0.44		4405	
	plastics	epoxy resin	-	24.581	7.71		77089	
	inorganic material	silicondioxide	60676-86-0	114.475	35.90	44.05	359015	440509
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11729	11729
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4455	4466
solder	noble metal	silver	7440-22-4	0.074	0.02		231	
	non noble metal	tin	7440-31-5	0.059	0.02		185	
	non noble metal	lead	7439-92-1	2.820	0.88	0.92	8843	9259
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	6.01	6.02	60144	60222
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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